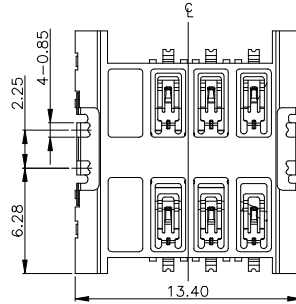
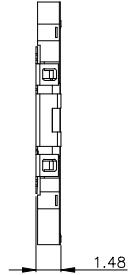
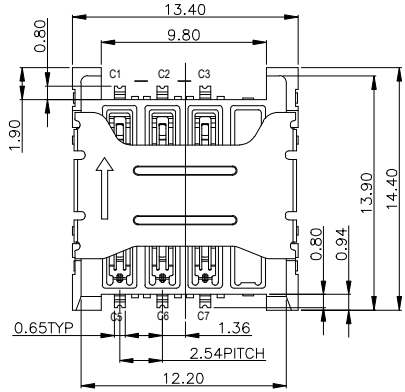
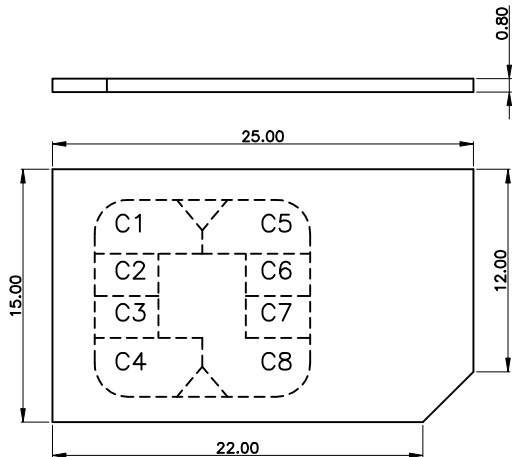
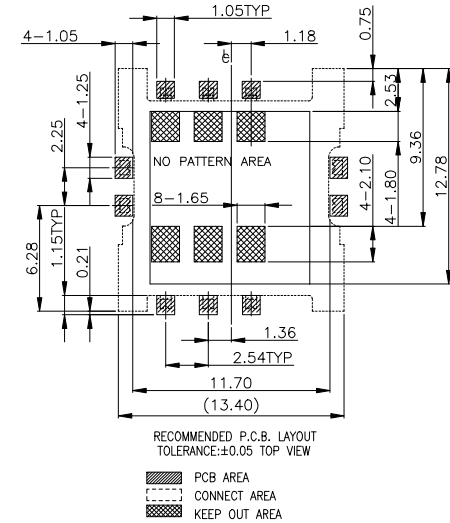
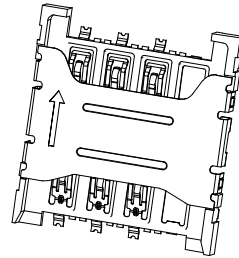
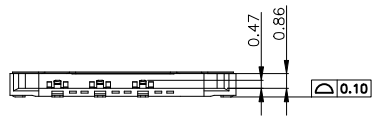




REV.	ECN NO OR DESCRIPTION	REVISED	DATE



pin no.	name
C1	vcc of sim
C2	rst of sim
C3	clk of sim
C5	gnd of sim
C6	vpp of sim
C7	I/O of sim
C4/C8	n/a



- MATERIALS**
- HOUSING THERMOPLASTIC (UL 94V-0) .
 - TERMINAL COPPER ALLOY, PLATING GOLD PLATED ON CONTACT AREA AND SOLDER TAILS,NICKEL PLATED OVERALL.
 - SHELL : STAINLESS STEEL. PLATING :NICKEL PLATED OVERALL. GOLD PLATED ON SOLDER TAILS

- SPECIFICATION**
- CURRENT RATING : 1.0 A MAX.
 - DIELECTRIC WITHSTANDING VOLTAGE : 500V AC R.M.S. FOR ONE MINUTE.
 - INSULATION RESISTANCE : >1000M MIN. AT 500V DC.
 - CONTACT RESISTANCE $\leq 30m$ MAX.
 - OPERATING TEMPERATURE : -40°C TO +85°C.

DESCRIPTION OF PLATING ON TERMINALS

NO.	EXPLAIN	NO.	EXPLAIN
0	GOLD FLASH	3	GOLD 15u''
1	GOLD 5u''	4	GOLD 20u''
2	GOLD 10u''	6	GOLD 30u''

UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS:	ANGLES:
X :±0.5	X :±2°
X.X :±0.20	X.X :±1°
X.XX :±0.10	



东莞市汉博电子科技有限公司
DONGGUAN HANBO TECHNOLOGY CO., LTD

TITLE	Mini sim card 6P 1.5H 防静电		
DWN	xiong	SIM-213	
CHKD	lee	SCALE:1:1	UNIT: mm
APVD	wang	SIZE: A4	SHEET:10F 1
			REV: A4

CUSTOMER COPY